

Access DB# 75423

# SEARCH REQUEST FORM

Scientific and Technical Information Center

Requester's Full Name: Julian Marcal Examiner #: 75795 Date: 9/11/02  
Art Unit: 1745 Phone Number 305-0511 Serial Number: 10/007,288  
Mail Box and Bldg/Room Location: 8E02 Results Format Preferred (circle): PAPER DISK E-MAIL

If more than one search is submitted, please prioritize searches in order of need.

\*\*\*\*\*  
Please provide a detailed statement of the search topic, and describe as specifically as possible the subject matter to be searched. Include the elected species or structures, keywords, synonyms, acronyms, and registry numbers, and combine with the concept or utility of the invention. Define any terms that may have a special meaning. Give examples or relevant citations, authors, etc, if known. Please attach a copy of the cover sheet, pertinent claims, and abstract.

Title of Invention: Method for making water-pow having sealed chamber  
Inventors (please provide full names): R. Wood, Jeffrey Rieley, Robert Higashi

Earliest Priority Filing Date: 3/1998

\*For Sequence Searches Only\* Please include all pertinent information (parent, child, divisional, or issued patent numbers) along with the appropriate serial number.

Please conduct litigation search for  
Re-Issue proceedings.

6,036,872

Thank you,

J. Marcal

No Litigation Reported

## STAFF USE ONLY

Type of Search		Vendors and cost where applicable
Searcher: <u>Mellerson</u>	NA Sequence (#) _____	STN _____
Searcher Phone #: <u>8-4483</u>	AA Sequence (#) _____	Dialog _____
Searcher Location: _____	Structure (#) _____	Questel/Orbit <u>40.52</u>
Date Searcher Picked Up: <u>9/11</u>	Bibliographic _____	Dr. Link _____
Date Completed: <u>9/11</u>	Litigation <input checked="" type="checkbox"/>	Lexis/Nexis <u>40.00</u>
Searcher Prep & Review Time: <u>2</u>	Fulltext _____	Sequence Systems _____
Clerical Prep Time: _____	Patent Family _____	WWW/Internet _____
Online Time: <u>6</u>	Other _____	Other (specify) _____

## Curr nt session 11/09/2002

(C) QUESTEL 1994

QUESTEL.ORBITE (TM) 1998

11/09/02 20\*54\*54

Last connection: 11/09/02 17\*18\*19

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- PlusPat Family w Legal Status in ONE record - INFO MFAMSTAT  
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- EPAPAT contains all unique EPTEXT data. EPTEXT file removed  
- New Patent Citation Commands: easy & precise - INFO PATCITE  
- USAPPS Reloaded: Pricing, see INFO USAPPS  
- USPCL: US Patent Class Definition Look-up File - INFO USPCL  
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### Query/Command : FILE PLUSPAT

QUESTEL - Time in minutes : 0,69

The cost estimation below is based on Questel's  
standard price list

	Estimated cost :	0.59 USD
Cost estimated for the last database search :		0.59 USD
Estimated total session cost	:	0.59 USD

Selected file: PLUSPAT

PLUSPAT - (c) Questel-Orbit, All Rights Reserved.  
Comprehensive Worldwide Patents database  
New Patent Citation Commands & FAM Citation Report - see INFO PATCITE  
Last update of file: 2002/09/11 (YYYY/MM/DD) 2002-36/UP (basic update)

Search statement 1

### Query/Command : US6036872/PN

#### \*\* SS 1: Results 1

Search statement 2

### Query/Command : PRT FULL NONSTOP LEGALALL

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*1 / 1 PLUSPAT - ©QUESTEL-ORBIT*

**PN** - US6036872 A 20000314 [US6036872]  
**TI** - (A) Method for making a wafer-pair having sealed chambers  
**PA** - (A) HONEYWELL INC (US)  
**IN** - (A) WOOD R ANDREW (US); RIDLEY JEFFREY A (US); HIGASHI ROBERT E (US)  
**AP** - US5264598 19980331 [1998US-0052645]  
**PR** - US5264598 19980331 [1998US-0052645]  
**IC** - (A) C23F-001/00  
**EC** - B81B-001/00  
H01L-027/16  
**PCL** - ORIGINAL (O) : 216002000; CROSS-REFERENCE (X) : 216024000 216033000  
216039000 216056000 438054000 438456000 438700000 438703000  
**DT** - Corresponding document  
**CT** - US4701424; US5366587; US5528452; US5585311; US5851631  
**STG** - (A) United States patent  
**AB** - A method for fabricating a wafer-pair having at least one recess in one wafer and the recess formed into a chamber with the attaching of the other wafer which has a port plugged with a deposited layer on its external surface. The deposition of the layer may be performed in a very low pressure environment, thus assuring the same kind of environment in the sealed chamber. The chamber may enclose at least one device such as a thermoelectric sensor, bolometer, emitter or other kind of device. The wafer-pair typically will have numerous chambers, with devices, respectively, and may be divided into a multiplicity of chips.  
**UP** - 2000-13

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*1 / 1 LGST - ©LEGSTAT*

**PN** - US 6036872 [US6036872]  
**AP** - US 52645/98 19980331 [1998US-0052645]  
**DT** - US-P  
**ACT** - 19980331 US/AE-A  
APPLICATION DATA (PATENT)  
US 52645/98 19980331 [1998US-0052645]  
  
20000314 US/A  
PATENT  
  
20020326 US/RF  
REISSUE APPLICATION FILED  
20011203  
**UP** - 2002-14

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**1 / 1 CRXX - ©CLAIMS/RRX**

**PN** - 6,036,872 A 20000314 [US6036872]  
**PA** - Honeywell Inc  
**ACT** - 20011203 REISSUE REQUESTED  
ISSUE DATE OF O.G.: 20020326  
REISSUE REQUEST NUMBER: 10/007288  
EXAMINATION GROUP RESPONSIBLE FOR REISSUEPROCESS: 1753

Reissue Patent Number:

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**1 / 1 PAST - ©Thomson Derwent**

**AN** - 200213-001635  
**PN** - 6036872 A [US6036872]  
**OG** - 2002-03-26  
**ACT** - REISSUE APPLICATION FILED

**Query/Command : FILE INPADOC**

**PLUSPAT** - Time in minutes : 0,70  
The cost estimation below is based on Questel's  
standard price list

Estimated cost :	1.54 USD
Records displayed and billed : 1	
Estimated cost :	1.10 USD
Cost estimated for the last database search :	2.64 USD
Estimated total session cost :	3.23 USD

**LGST** - Time in minutes : 0,14  
The cost estimation below is based on Questel's  
standard price list

Estimated cost :	0.15 USD
Records displayed and billed : 1	
Estimated cost :	0.57 USD
Legal-Status informations : 1	
Estimated cost :	4.92 USD
Cost estimated for the last database search :	5.64 USD
Estimated total session cost :	8.87 USD

**CRXX** - Time in minutes : 0,07  
The cost estimation below is based on Questel's  
standard price list

Estimated cost :	0.10 USD
Records displayed and billed : 1	
Estimated cost :	5.00 USD
Legal-Status informations : 1	
Estimated cost :	4.92 USD
Cost estimated for the last database search :	10.02 USD
Estimated total session cost :	18.89 USD

**PAST** - Time in minutes : 0,06  
The cost estimation below is based on Questel's  
standard price list

Estimated cost :	0.11 USD
Records displayed and billed : 1	



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**2 / 5 INPADOC - ©INPADOC**

**PN** - EP 1070353 A1 20010124 [EP1070353]  
**TI** - A METHOD FOR MAKING A WAFER-PAIR HAVING SEALED CHAMBERS  
**LA** - ENG  
**IN** - WOOD R ANDREW [US]; RIDLEY JEFFREY A [US]; HIGASHI ROBERT E [US]  
**PA** - HONEYWELL INC [US]  
**AP** - EP 99914273/99-A 19990330 [1999EP-0914273]  
**PR** - WO 9906890/99(US)-W 19990330 [1999WO-US06890]  
US 52645/98-A 19980331 [1998US-0052645]  
**IC** - H01L-027/16; G01J-005/20  
**DS** - DE\* FR\* GB\*

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**1 / 1 LEGALI - ©LEGSTAT**

**PN** - EP 1070353 [EP1070353]  
**AP** - EP 99914273/99 19990330 [1999EP-0914273]  
**DT** - EP-P  
**ACTE** - 19990330 EP/AE-A  
EP-APPLICATION  
EP 99914273/99 19990330 [1999EP-0914273]  
  
20010124 EP/AK-A1 [+]  
DESIGNATED CONTRACTING STATES IN AN APPLICATION WITH SEARCH  
REPORT:  
DE FR GB  
  
20010124 EP/A1 [+]  
PUBLICATION OF APPLICATION WITH SEARCH REPORT  
  
20010124 EP/17P [+]  
REQUEST FOR EXAMINATION FILED  
20000928  
**UP** - 2001-04

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**3 / 5 INPADOC - ©INPADOC**

**PN** - JP 2002510865 T2 20020409 [JP2002510865]  
**AP** - JP 2000541738/00-A 19990330 [2000JP-0541738]  
**PR** - US 52645/98-A 19980331 [1998US-0052645]  
WO 9906890/99(US)-W 19990330 [1999WO-US06890]  
**IC** - H01L-037/02; G01J-001/02

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*4 / 5 INPADOC - ©INPADOC*

**PN** - US 6036872 A 20000314 [US6036872]  
**TI** - METHOD FOR MAKING A WAFER-PAIR HAVING SEALED CHAMBERS  
**IN** - WOOD R ANDREW [US]; RIDLEY JEFFREY A [US]; HIGASHI ROBERT E [US]  
**PA** - HONEYWELL INC [US]  
**AP** - US 52645/98-A 19980331 [1998US-0052645]  
**PR** - US 52645/98-A 19980331 [1998US-0052645]  
**IC** - C23F-001/00

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*1 / 1 LEGALI - ©LEGSTAT*

**PN** - US 6036872 [US6036872]  
**AP** - US 52645/98 19980331 [1998US-0052645]  
**DT** - US-P  
**ACTE** - 19980331 US/AE-A  
APPLICATION DATA (PATENT)  
US 52645/98 19980331 [1998US-0052645]  
  
20000314 US/A  
PATENT  
  
20020326 US/RF  
REISSUE APPLICATION FILED  
20011203  
**UP** - 2002-14

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*5 / 5 INPADOC - ©INPADOC*

**PN** - WO 9950913 A1 19991007 [WO9950913]  
**TI** - A METHOD OF MAKING A WAFER-PAIR HAVING SEALED CHAMBERS  
**LA** - ENG  
**IN** - WOOD R ANDREW; RIDLEY JEFFREY A; HIGASHI ROBERT E  
**PA** - HONEYWELL INC [US]  
**AP** - WO US 9906890/99(US)-A 19990330 [1999WO-US06890]  
**PR** - US 52645/98-A 19980331 [1998US-0052645]  
**IC** - H01L-027/16; G01J-005/20  
**DS** - CA\* JP\* AT BE CH CY DE DK ES FI FR GB GR IE IT LU MC NL PT SE

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1 / 3 LEGALI - ©LEGSTAT

PN - JP 541738/2000  
 AP - JP 541738/2000 0 [2000JP-0541738]  
 DT - JP-A  
 ACTE - 20001002 JP/REFW-P  
 CORRESPONDS TO PCT APPLICATION  
 <WO 9950913> WO9950913  
 UP - 2002-09

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2 / 3 LEGALI - ©LEGSTAT

PN - CA 2326677 [CA2326677]  
 DT - CA-P  
 ACTE - 20000929 CA/REFW-P  
 CORRESPONDS TO PCT APPLICATION  
 <WO 9950913> [WO9950913]  
 UP - 2001-11

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3 / 3 LEGALI - ©LEGSTAT

PN - WO 9950913 [WO9950913]  
 AP - WO 9906890/99(US) 19990330 [1999WO-US06890]  
 DT - WO-P  
 ACTE - 19990330 WO/AE-A  
 APPLICATION DATA  
 WO 9906890/99(US) 19990330 [1999WO-US06890]  
  
 19991007 WO/AK-A1 [+]  
 DESIGNATED STATES CITED IN A PUBLISHED APPLICATION WITH SEARCH  
 REPORT  
 CA JP  
  
 19991007 WO/AL-A1 [+]  
 DESIGNATED COUNTRIES FOR REGIONAL PATENTS CITED IN A PUBLISHED  
 APPLICATION WITH SEARCH REPORT  
 AT BE CH CY DE DK ES FI FR GB GR IE IT LU MC NL PT SE  
  
 19991007 WO/A1 [+]  
 PUBLICATION OF THE INTERNATIONAL APPLICATION WITH THE  
 INTERNATIONAL SEARCH REPORT  
  
 19991201 WO/121  
 EP: THE EPO HAS BEEN INFORMED BY WIPO THAT EP WAS DESIGNATED IN  
 THIS APPLICATION  
  
 19991216 WO/DFPE  
 REQUEST FOR PRELIMINARY EXAMINATION FILED PRIOR TO EXPIRATION  
 OF 19TH MONTH FROM PRIORITY DATE  
  
 20000929 WO/ENP-AA



20000929 WO/ENP-AA  
ENTRY INTO THE NATIONAL PHASE IN:  
<CA 2326677>

20001002 WO/ENP-A  
ENTRY INTO THE NATIONAL PHASE IN:  
<JP 00541738>

**UP** - 2002-09

PATNO IS 6036872

DATE: SEPTEMBER 11, 2002  
LIBRARY: PATENT  
FILE: ALL

Your search request is:  
PATNO IS 6036872

Number of PATENTS found with your search request through:  
LEVEL 1... 1

Your search request has found 1 PATENT through Level 1.  
To DISPLAY this PATENT press either the KWIC, FULL, CITE or SEGMENTS key.  
To MODIFY your search request, press the M key (for MODIFY) and then the ENTER key.

For further explanation, press the H key (for HELP) and then the ENTER key.

LEVEL 1 - 1 PATENT

1. 6036872 , March 14, 2000 , Method for making a wafer-pair having sealed chambers , Wood, R. Andrew, Bloomington, MN; Ridley, Jeffrey A., Burnsville, MN; Higashi, Robert E., Shorewood, MN, 00052645 (), Honeywell Inc., Minneapolis, MN

CORE TERMS: wafer, layer, vacuum, sub, detector, chamber, cavity, deposited, angstrom, port ...

LEVEL 1 - 1 OF 1 PATENT

UNITED STATES PATENT AND TRADEMARK OFFICE GRANTED PATENT

6036872

<=1> GET 1st DRAWING SHEET OF 4

March 14, 2000

Method for making a wafer-pair having sealed chambers

REISSUE: December 3, 2001 - Reissue Application filed Dec. 3, 2001 (O.G. Mar. 26, 2002) Ex. Gp.: 1753; Re. S.N. 10/007,288 March 26, 2002

APPL-NO: 00052645 ()

FILED-DATE: March 31, 1998

GRANTED-DATE: March 14, 2000

CORE TERMS: wafer, layer, vacuum, sub, detector, chamber, cavity, deposited, angstrom, port ...

ENGLISH-ABST:

A method for fabricating a wafer-pair having at least one recess in one wafer and the recess formed into a chamber with the attaching of the other wafer which has a port plugged with a deposited layer on its external surface. The deposition of the layer may be performed in a very low pressure environment, thus assuring the same kind of environment in the sealed chamber. The chamber may enclose at least one device such as a thermoelectric sensor, bolometer, emitter or other kind of device. The wafer-pair typically will have numerous chambers, with devices, respectively, and may be divided into a multiplicity of chips.

6036872 OR 6,036,872

Your search request has found no CASES.

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To enter a new search request, type it and press the ENTER key.

What you enter will be Search Level 1.

For further explanation, press the H key (for HELP) and then the ENTER key.